Wideband Amplifier RFC1G21H4-24

Product Features

- GaN on SiC MMIC
- Very Low Distortion
- Guaranteed Broadband Power Gain
- Heat Sink 99.9% Copper, Ag or Gold Plate
- Excellent Thermal Conductivity
- Single Supply Voltage @ 24V
- No External Circuit needed

Applications

- Drive Amplifier

Package Type : DP-27

Description

The RFC1G21H4- 24 is specifically designed for up to 1GHz in frequency as amplifiers.
This hybrid dynamic range amplifier module operates with a single voltage supply of 24V(DC).
The RFC1G21H4- 24 is equipped with over-voltage suppressor.

Electrical Specifications @ V_{DD} = 24V, T_A = 25°C

PARAMETER	UNIT	MIN	TYP	MAX	CONDITION
Operating Frequency	MHz	20	-	1000	-
Gain	dB	20.0	21.0	-	f = 1000MHz
Gain Flatness	dB	-	1.5	2.0	f = 20 ~ 1000MHz
Input / Output VSWR	-	2.5 : 1	2.0 : 1	-	-
IP3	dBm	43.0	44.0	-	Total Pout = 23dBm. Tone spacing 1MHz
Power Output 3dB Comp.	dBm	35.0	36.0	-	f = 20 ~ 1000MHz
Supply Current	mA	-	550	600	-

Absolute Maximum Ratings

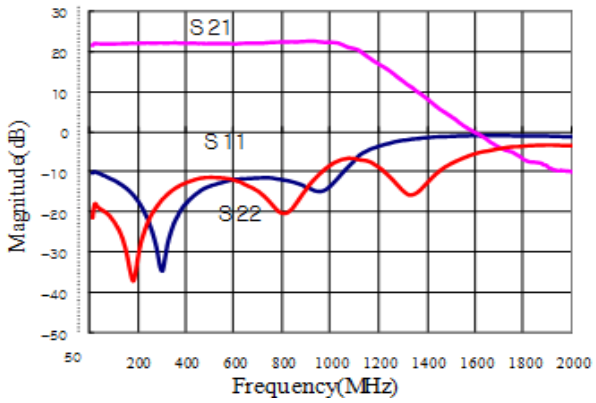
PARAMETER	UNIT	MIN	TYP	MAX	CONDITION
V_{DD} / V_{RFOUT}	VDC	20	-	28	-
RF_{OUT}	dBm	22	-	38	Single Tone
Storage Temperature	℃	-40	-	105	-
Operating Temperature	℃	-20	-	80	-

Note
1. To protect the unit, VDD Voltage under 18V, the unit will be switched off.

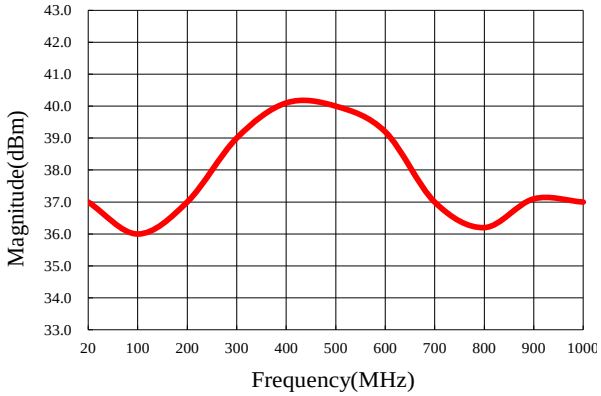
Typical Performance @ 25°C

PARAMETER	UNIT	TYP		
Frequency	MHz	20	500	1000
Gain	dB	21	21	22
Input Return Loss	dB	-10	-13	-13
Output Return Loss	dB	-17	-11	-8
P3dB	dBm	36	39	37
OIP3	dBm	45	47	44
Supply Voltage	V	-	24	-
Current	mA	-	550	-

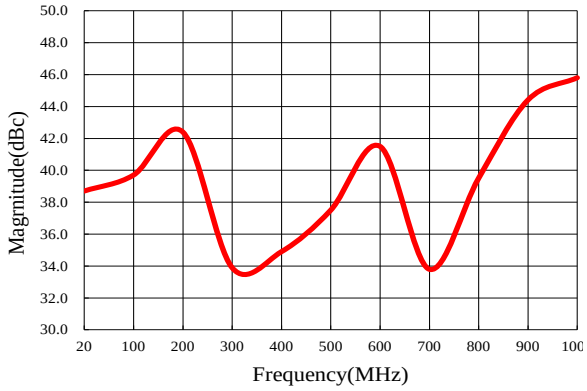
S-Parameters



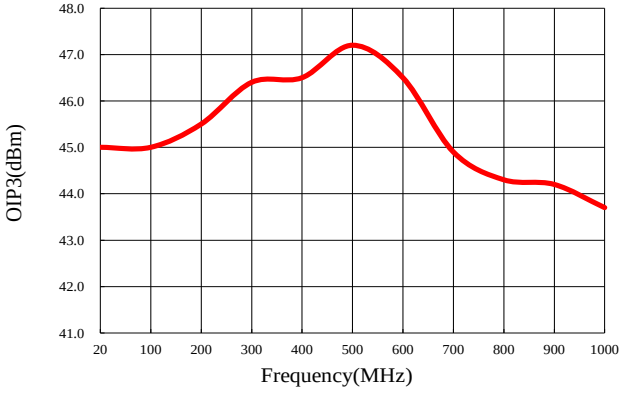
Power Output 3dB Compression



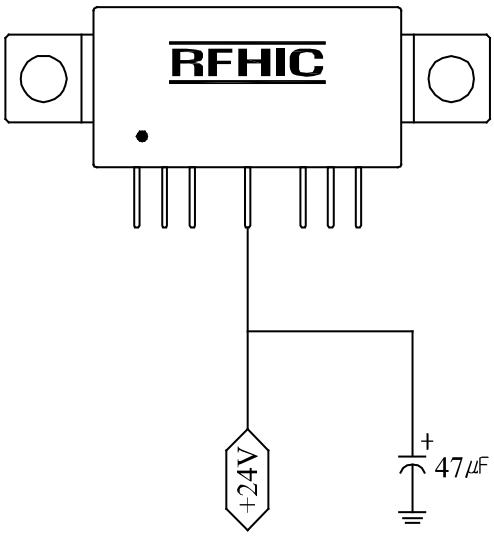
2nd Harmonic @ Po 30dBm



OIP 3 @ Po 23dBm



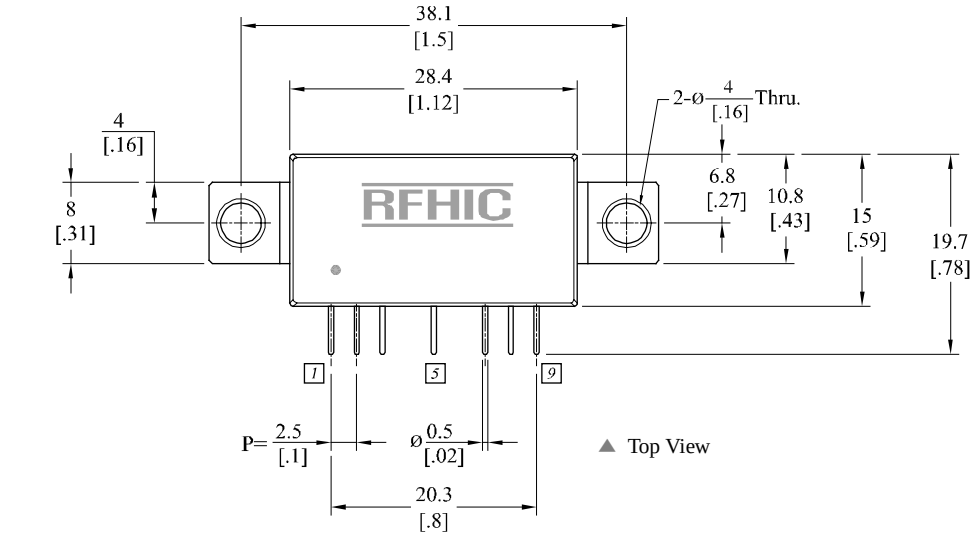
Note for Correct Use



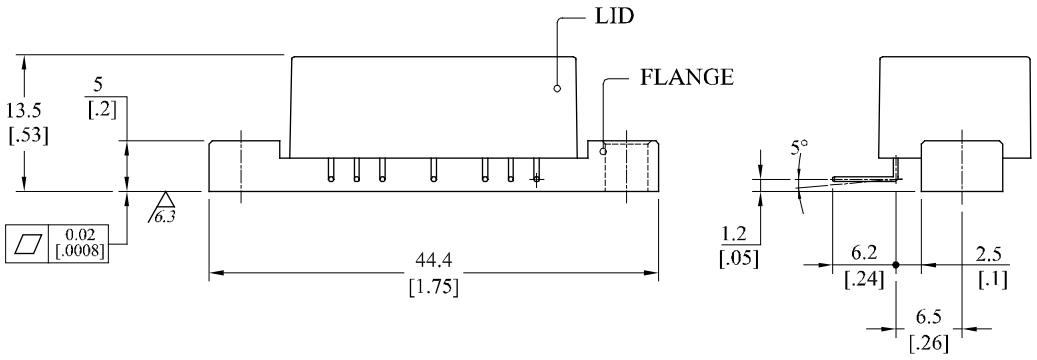
1. On the power input port (Pin#5), 47uF/35V capacitor GND is recommended.
2. Heat sink should be placed as tight as possible to the metal case.
3. Pay attention when handling electrostatic-sensitive devices.
- Person at a workbench should be earthed via a wrist strap and a resistor.
- All mains-powered equipment should be connected to the mains via an earth-leakage switch.
- Equipment cases should be grounded.
- Relative humidity should be maintained between 40% and 50%.
- An ionizer is recommended.
- Keep static materials, such as plastic envelopes and plastic trays etc., away from the workbench.
4. One must put the power off, before adjusting the in/output matching of the system.
5. Pay close attention to the input voltage not to over power the hybrid.
6. Do not open the Plastic cover to change the matching inside the hybrid.

Package Dimensions (Type: DP-27)

* Unit: mm[inch] | Tolerance: ±0.2[.008]



▲ Top View



▲ Front View ▲ Side View

Pin Description					
Pin No	**Function**	**Pin No**	**Function**	**Pin No**	**Function**
1	RF Input	4		7	GND
2	GND	5	Vcc	8	GND
3	GND	6		9	RF Output

*** Mounting Configuration Notes**

1. Ground / thermal via holes are critical for the proper performance of this device.
2. Add as much copper as possible to inner and outer layers near the part to ensure optimal thermal performance.
3. Mounting screws can be added near the part to fasten the board to a heatsink. Ensure that the ground / thermal via hole region contacts the heatsink.
4. Do not put solder mask on the backside of the PCB in the region where the board contacts the heatsink.
5. RF trace width depends upon the PCB material and construction.
6. Use 1 oz. Copper minimum.

Revision History

Part Number	Release Date	Version	Modification	Data Sheet Status
RFC1G21H4-24	2012.11.6	1.4	Electrical Specifications modification	-
RFC1G21H4-24	2012.9.5	1.3	-	-